



Product Change Notification

Change Notification #: 116711 - 00
Change Title: Intel® Server System R2224WTTYSR,
PCN 116711-00, Product Design,
BIOS/ME/BMC Firmware factory,
Hot-Swap Back Plane Firmware Update
Date of Publication: January 14, 2019

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	January 30, 2019
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® Server System R2224WTTYSR:

1. Update the BIOS to revision R01.01.2024.
2. Update the Manageability Engine (ME) firmware to revision 03.01.03.043.
3. Update the Integrated Baseboard Management Controller (BMC) firmware to revision 01.51.11142. Intel Server Boards with factory firmware will display the following message on each boot until the BIOS is updated:
"WARNING: This Server is running factory firmware. A software update is required. As part of your system integration process, please load the latest system update package (SUP) to enable the latest security, quality and performance."
4. Intel is updating the Hot-Swap Back Plane (HSBP) firmware from version 1.40 to 1.41 of the Intel Server Systems listed in the "Products Affected" table below. The firmware version 1.41 fixes a fault LED issue found on manufacturing.

Customer Impact of Change and Recommended Action:

The primary value of this factory BIOS is that it allows the customer to perform a single BIOS programming (upgrade or downgrade) without the requirement of moving the BIOS Recovery physical jumper. Once the first programming is done, any subsequent attempts to downgrade will require moving the BIOS Recovery physical jumper

Intel does not expect any other impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation. Customers can download and evaluate the latest BIOS/ME/Integrated BMC and FRUSDR release notes for more information at <http://www.intel.com/support>.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
R2224WTTYSR	943831	J11492-011	J11492-012

PCN Revision History:

Date of Revision:

January 14, 2019

Revision Number:

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Reason:

Originally Published PCN



Product Change Notification

116711 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

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